

METHOD FOR FABRICATING SILICON TARGETS

ABSTRACT OF THE INVENTION

A method for fabricating silicon tiles and silicon tile targets
5 has been provided, such as may be used in the sputter deposition of thin
film transistor (TFT) silicon films. The method describes processes of
cutting the tiles, beveling the tiles edges, etching the tiles to minimize
residual damage caused by cutting the tiles, polishing the tiles to a
specified flatness, and attaching the tiles to a backing plate. All these
10 processes are performed with the aim of minimizing contamination and
particle formations when the target is used for sputter deposition.